

L Number	Hits	Search Text	DB	Time stamp
1	372	73/204.26.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 15:06
2	160	73/204.15.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 15:06
3	127	73/204.18.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 15:06
4	372	73/204.26.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 15:06
5	83	73/204.16.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 15:06
6	75	73/204.24.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 15:06
7	107	73/204.23.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 15:06
8	52	(73/204.26.ccls. 73/204.15.ccls. 73/204.18.ccls. 73/204.26.ccls. 73/204.16.ccls. 73/204.ccls. 73/204.24.ccls. 73/204.23.ccls.) and ((frame structure base layer film) near4 silicon\$2) and ((heat\$4 therm\$5) near5 (frame structure base layer film)) and ((frame structure base layer film) near4 (thermometer temperature) near4 (measur\$4 meter\$4 determin\$4 detect\$4 asses\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 15:08
-	279	73/204.26.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 15:06
-	9	("5423212" "5393351" "5703287").pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/24 17:06
-	200	73/204.26.ccls. and (membrane coat\$4 layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/24 17:19
-	1	73/204.26.ccls. and (membrane coat\$4 layer) and impermeable	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/24 17:19
-	2	("4682503" "4766666").PN.	USPAT	2002/01/24 17:20

	27	4766666.URPN.	USPAT	2002/01/24 17:20
	64	73/204.26.ccls. and silicon and nitride	USPAT; USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/24 18:05
	58	73/204.26.ccls. and silicon and nitride and (heat\$4 therm\$5) and (insulat\$5 imperm\$6 membrane)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/24 18:20
	55	73/204.26.ccls. and silicon and nitride and (heat\$4 therm\$5) and (insulat\$5 imperm\$6 membrane) and (temperat\$5 near2 (sens\$4 measur\$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/25 15:21
	17	73/204.26.ccls. and silicon and nitride and (heat\$4 therm\$5) and (insulat\$5 imperm\$6 seal\$5) and membrane and (temperat\$5 near2 (sens\$4 measur\$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/24 19:03
	15	73/204.26.ccls. and silicon and nitride and (heat\$4 therm\$5) and (insulat\$5 imperm\$6 seal\$5) and membrane and (temperat\$5 near2 (sens\$4 measur\$6)) and (contact terminal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/24 20:35
	14	73/204.26.ccls. and silicon and nitride and (heat\$4 therm\$5) and (insulat\$5 imperm\$6 seal\$5) and membrane and (temperat\$5 near2 sens\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/14 14:20
	3	73/204.26.ccls. and carbide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/24 20:36
	25	("5393351" "5852239" "5423212" "5703287" "6318170" "6290388" "6240777" "5965813" "4682503" "4545650").pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/01/25 10:42
	4	(("si.sub.3.n.sub.4.") or (silicon? near2 nitride)) and (heat\$4 therm\$5) and ((no? near3 permea\$4) imperm\$6) and (temperat\$5 near2 (sens\$4 detect\$4 determin\$4 meter\$4 measur\$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/25 15:44
	0	"si.sub.3.n.sub.4."	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/25 15:46
	1	"si.sub.3-n.sub.4"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/25 15:49
	17387	"si.sub.3 n.sub.4"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/25 15:49

	51	("si.sub.3 n.sub.4" or (silicon? near2 nitride)) and ((no? near3 permea\$4) imperm\$6) and (temperat\$5 near2 (sens\$4 detect\$4 determin\$4 meter\$4 measur\$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/25 16:52
	4	("si.sub.3 n.sub.4" or (silicon? near2 nitride)) same ((no? near3 permea\$4) imperm\$6) and (temperat\$5 near2 (sens\$4 detect\$4 determin\$4 meter\$4 measur\$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/25 15:58
	6	("si.sub.3 n.sub.4" or (silicon? near2 nitride)) same ((no? near3 permea\$4) imperm\$6) and ((temperat\$5 heat) near2 (sens\$4 detect\$4 determin\$4 meter\$4 measur\$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/25 16:19
	64	("si.sub.3 n.sub.4" or (silicon? near2 nitride)) and ((water near2 repel\$5) or (no? near3 permea\$4) or impermea\$6) and (temperat\$5 near2 (sens\$4 detect\$4 determin\$4 meter\$4 measur\$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/25 16:15
	17	(("si.sub.3 n.sub.4" or (silicon? near2 nitride)) and ((water near2 repel\$5) or (no? near3 permea\$4) or impermea\$6) and (temperat\$5 near2 (sens\$4 detect\$4 determin\$4 meter\$4 measur\$6))) and sandw\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/25 16:15
	17	("si o.sub.2" or (silicon? near2 oxide)) near6 (recess hole hollow cavity gap)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/25 16:54
	553	((frame structure base layer film) near4 silicon\$2) and (silicon\$2 near4 nitride) and (heat\$4 therm\$5) and (insulat\$5 imperm\$6 seal\$5) and (diaphragm membrane) and (((temperat\$5 heat thermal) near2 sens\$4) or thermometer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/14 14:52
	332	(((frame structure base layer film) near4 silicon\$2) and (silicon\$2 near4 nitride) and (heat\$4 therm\$5) and (insulat\$5 imperm\$6 seal\$5) and (diaphragm membrane) and (((temperat\$5 heat thermal) near2 sens\$4) or thermometer)) and ((sens\$4 measur\$4 determin\$4 estimat\$4 detect\$4) near4 (flow volume mass))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/14 15:13
	95	(((frame structure base layer film) near4 silicon\$2) and (silicon\$2 near4 nitride) and (heat\$4 therm\$5) and (insulat\$5 imperm\$6 seal\$5) and (diaphragm membrane) and (((temperat\$5 heat thermal) near2 sens\$4) or thermometer)) and ((sens\$4 measur\$4 determin\$4 estimat\$4 detect\$4) near4 (flow volume mass))) and 73/\$6.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/23 16:22
	4	("5965811" "5237867").pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/15 13:18
	348	73/204.26.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/23 16:08
	155	73/204.15.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 15:06

-	124	73/204.18.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 15:06
-	348	73/204.26.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 15:06
-	83	73/204.16.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 15:06
-	73	73/204.24.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 15:06
-	105	73/204.23.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 15:06
-	44	(73/204.26.ccls. 73/204.15.ccls. 73/204.18.ccls. 73/204.26.ccls. 73/204.16.ccls. 73/204.ccls. 73/204.24.ccls. 73/204.23.ccls.) and ((frame structure base layer film) near4 silicon\$2) and ((heat\$4 therm\$5) near5 (frame structure base layer film)) and ((frame structure base layer film) near4 (thermometer temperature) near4 (measur\$4 meter\$4 determin\$4 detect\$4 asses\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 15:06
-	2	5703287.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/29 16:26